

**PATENT ASSIGNMENT**

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT								
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT								
<b>CONVEYING PARTY DATA</b>									
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Leilei Song</td> <td>08/13/2007</td> </tr> <tr> <td>Jungwon Lee</td> <td>08/13/2007</td> </tr> <tr> <td>Woong Jun Jang</td> <td>08/14/2007</td> </tr> </tbody> </table>		Name	Execution Date	Leilei Song	08/13/2007	Jungwon Lee	08/13/2007	Woong Jun Jang	08/14/2007
Name	Execution Date								
Leilei Song	08/13/2007								
Jungwon Lee	08/13/2007								
Woong Jun Jang	08/14/2007								
<b>RECEIVING PARTY DATA</b>									
<b>Name:</b>	Marvell Semiconductor, Inc.								
<b>Street Address:</b>	5488 Marvell Lane								
<b>City:</b>	Santa Clara								
<b>State/Country:</b>	CALIFORNIA								
<b>Postal Code:</b>	95054								
<b>PROPERTY NUMBERS Total: 2</b>									
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>60822827</td> </tr> <tr> <td>Application Number:</td> <td>11839004</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	60822827	Application Number:	11839004		
Property Type	Number								
Application Number:	60822827								
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<b>CORRESPONDENCE DATA</b>									
<b>Fax Number:</b>	(646)728-2915								
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>									
<b>Email:</b>	andrew.shiue@ropesgray.com								
<b>Correspondent Name:</b>	Michael J. Chasan								
<b>Address Line 1:</b>	1211 Avenue of the Americas								
<b>Address Line 2:</b>	Ropes & Gray LLP								
<b>Address Line 4:</b>	New York, NEW YORK 10036-8704								
<b>ATTORNEY DOCKET NUMBER:</b>	004048-0094 (MP1264)								
<b>NAME OF SUBMITTER:</b>	Michael J. Chasan								

CH \$80.00 60822827

Total Attachments: 2  
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Docket#: MP1264

PATENT

**ASSIGNMENT**

For good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned,

**Leilei Song, Jungwon Lee and Woong Jun Jang**

who have created a certain invention for which an application for United States Letters Patent was executed by us concurrently herewith and entitled:

**LOW-COMPLEXITY SCALABLE ARCHITECTURE FOR  
CONCATENATION-ASSISTED SYMBOL-LEVEL COMBINING**

Do hereby sell, assign and transfer to Marvell Semiconductor, Inc., a corporation of California, having a place of business at 5488 Marvell Lane, Santa Clara, CA 95054, its successors, assigns, and legal representatives, the full and exclusive right to said invention and said application and to any and all inventions described in said application for the United States, its territorial possessions and all foreign countries, and the entire right, title and interest in and to any and all Letters Patent which may be granted therefor in the United States, its territorial possessions and all foreign countries; and in and to any and all continuations-in-part, continuations, divisions, substitutes, reissues, extensions thereof, and all other applications for Letters Patent relating thereto which have been or shall be filed in the United States, its territorial possessions and/or any foreign countries, and all rights, together with all priority rights, under any of the international conventions, unions, agreements, acts, and treaties, including all future conventions, unions, agreements, acts, and treaties;

Do hereby further sell, assign and transfer to Marvell Semiconductor, Inc., its successors, assigns, and legal representatives, the full and exclusive right to United States Provisional Patent Applications(s) No(s). 60/822,827 filed August 18, 2006, and to any and all inventions described in said provisional patent application(s) for the United States, its territorial possessions and all foreign countries, and the entire right, title and interest in and to any and all Letters Patent which may be entitled to the benefit thereof in the United States, its territorial possessions and all foreign countries; and in and to any and all continuations-in-part, continuations, divisions, substitutes, reissues, extensions thereof, and all other applications for Letters Patent relating thereto which have been or shall be filed in the United States, its territorial possessions and/or any foreign countries, and all rights, together with all priority rights, under any of the international conventions, unions, agreements, acts, and treaties, including all future conventions, unions, agreements, acts, and treaties;


Agree that Marvell Semiconductor, Inc., hereinafter referred to as Assignee, may apply for and receive Letters Patent for said invention and said inventions, hereinafter referred to as said invention, in its own name, in the United States, its territorial possessions, and all foreign countries; and that, when requested to carry out in good faith the intent and purpose of this assignment, at the expense of said Assignee, its successors, assigns and legal representatives, the undersigned will execute all continuations-in-part, continuations, divisions, substitutes, reissues, extensions thereof, execute all rightful oaths, assignments, powers of attorney and other papers, testify in any legal or quasi legal proceedings; communicate to said Assignee, its successors, assigns or legal representatives all facts known to the undersigned relating to said invention and the history thereof; and generally do everything possible which said Assignee, its successors, assigns, or legal representatives shall consider desirable for aiding in securing, maintaining and enforcing proper patent protection for said invention and for vesting title to said invention and all applications for patents on said invention in said Assignee, its successors, assigns, or legal representatives; and


Covenant with said Assignee, its successors, assigns, or legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.


PATENT

REEL: 019804 FRAME: 0809

IN TESTIMONY WHEREOF we have hereunto set OUR signatures on the dates indicated below.

Full Name of First Inventor:	
Leilei Song	
Inventor's Signature:	Date: Month/Day/Year
	08/13/2007

Full Name of Second Inventor:	
Jungwon Lee	
Inventor's Signature:	Date: Month/Day/Year
	8/13/07

Full Name of Third Inventor:	
Woong Jun Jang	
Inventor's Signature:	Date: Month/Day/Year
	8/14/2007